

STGF10NB60SD STGP10NB60SD

16 A, 600 V, low drop IGBT with soft and fast recovery diode

Features

- Low on-voltage drop (V_{CE(sat)})
- High current capability
- Very soft ultra fast recovery antiparallel diode

Applications

- Light dimmer
- Static relays
- Motor drive

Description

This IGBT utilizes the advanced Power MESH[™] process featuring extremely low on-state voltage drop in low-frequency working conditions (up to 1 kHz).

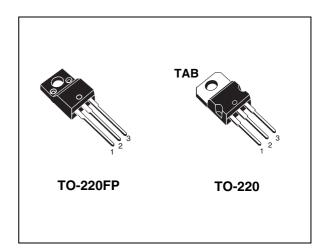


Figure 1. Internal schematic diagram

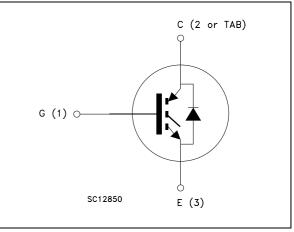


Table 1.Device summary

Order codes	Marking	Package	Packaging
STGF10NB60SD	GF10NB60SD	TO-220FP	Tube
STGP10NB60SD	GP10NB60SD	TO-220	Tube

September	2011
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Doc ID 11860 Rev 3

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1 Electrical ratings

Symbol	Parameter	Va	Unit	
Symbol	Falameter	STGF10NB60SD	STGP10NB60SD	Omt
V _{CES}	Collector-emitter voltage (V _{GE} = 0)	600		V
I _C ⁽¹⁾	Continuous collector current at $T_C = 25$ °C	23	23 29	
I _C ⁽¹⁾	Continuous collector current at $T_{C} = 100 \text{ °C}$	12 16		A
I _{CL} ⁽²⁾	Turn-off latching current	20		А
I _{CP} ⁽³⁾	Pulsed collector current	80		А
V _{GE}	Gate-emitter voltage	±20		V
١ _F	Diode RMS forward current at $T_C = 25 \ ^{\circ}C$	20		А
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$	55		А
V _{ISO}	Isolation withstand voltage (RMS) from all three leads to external heatsink (t=1 s; $T_C = 25$ °C)	2500		v
P _{TOT}	Total dissipation at $T_{C} = 25 \text{ °C}$	25	80	W
Тj	Operating junction temperature	- 55	to 150	°C

Table 2.Absolute maximum ratings

1. Calculated according to the iterative formula

$$I_{C}(T_{C}) = \frac{T_{j(max)} - T_{C}}{R_{thj-c} \times V_{CE(sat)(max)}(T_{j(max)}, I_{C}(T_{C}))}$$

2. Vclamp = 80% of V_{CES}, T_j =150 °C, R_G=1k $\Omega,$ V_GE=15 V

3. Pulse width limited by maximum junction temperature and turn-off within RBSOA

	Table 3	3.	Thermal	data
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Symbol		Parameter	Val	Unit	
		i arameter	STGF10NB60SD	STGP10NB60SD	Onit
	R _{thj-case}	Thermal resistance junction-case IGBT	5	1.56	°C/W
	R _{thj-case}	Thermal resistance junction-case diode	5.6	5.6 2.2	
	R _{thj-amb}	Thermal resistance junction-ambient	62.5		°C/W

2 Electrical characteristics

(T_j =25 °C unless otherwise specified)

Table 4.	Static
	Otatio

			1	1		
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)CES}	Collector-emitter breakdown voltage (V _{GE} = 0)	I _C = 250 μΑ	600			۷
V _{(BR)ECS}	Emitter-collector breakdown voltage (V _{GE} = 0)	I _C = 1 mA	20			٧
I _{GES}	Gate-emitter leakage current (V _{CE} = 0)	V _{GE} = ±20 V			±100	nA
I _{CES}	Collector cut-off current (V _{GE} = 0)	V _{CE} = 600 V V _{CE} = 600 V, T _j = 125 °C			10 100	μΑ μΑ
V _{GE(th)}	Gate threshold voltage	V_{CE} = V_{GE} , I_C = 250 μ A	2.5		5	V
V _{CE(sat)}	Collector-emitter saturation voltage	V_{GE} = 15 V, I _C = 5 A V_{GE} = 15 V, I _C = 10 A V_{GE} = 15 V, I _C = 10 A, T_{j} = 125 °C		1.15 1.35 1.25	1.75	V
g_{fs} ⁽¹⁾	Forward transconductance	$V_{CE} = 15 V_{,I_{C}} = 10 A$	5			S

1. Pulsed: Pulse duration = 300 μ s, duty cycle 1.5%

Table 5.	Dynamic
	bynanno

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{ies} C _{oes} C _{res}	Input capacitance Output capacitance Reverse transfer capacitance	V _{CE} = 25 V, f = 1 MHz, V _{GE} = 0	-	610 65 12	-	pF pF pF
Qg	Total gate charge	$V_{CE} = 400 \text{ V}, I_C = 10 \text{ A},$ $V_{GE} = 15 \text{ V}$ (see Figure 19)	-	33	-	nC



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 480 \text{ V}, I_C = 10 \text{ A}$ $R_G = 1 \text{ k}\Omega, V_{GE} = 15 \text{ V}$ (see Figure 18)	-	0.7 0.46 8	-	μs μs A/μs
t _r (V _{off}) t _d (_{off}) t _f	Off voltage rise time Turn-off delay time Current fall time	V _{CC} = 480 V, I _C = 10 A R _G = 1 kΩ, V _{GE} = 15 V (<i>see Figure 18</i>)	-	2.2 1.2 1.2	-	μs
t _r (V _{off}) t _{d(off}) t _f	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 480 \text{ V}, I_C = 10 \text{ A}$ $R_G = 1 \text{ k}\Omega, V_{GE} = 15 \text{ V},$ $T_j = 125 \text{ °C}$ <i>(see Figure 18)</i>	-	3.8 1.2 1.9	-	μs

Table 6. Switching on/off (inductive load)

Table 7. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Eon ⁽¹⁾ E _{off} ⁽²⁾ E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 480 \text{ V}, I_{C} = 10 \text{ A}$ $R_{G} = 1 \text{ k}\Omega, V_{GE} = 15 \text{ V}$ <i>(see Figure 18)</i>	-	0.6 5 5.6	-	mJ mJ mJ
E _{off} ⁽²⁾	Turn-off switching losses	$V_{CC} = 480 \text{ V}, I_C = 10 \text{ A}$ $R_G = 1 \text{ k}\Omega, V_{GE} = 15 \text{ V},$ $T_j = 125 \text{ °C}$ <i>(see Figure 18)</i>	-	8	-	mJ

 Eon is the turn-on losses when a typical diode is used in the test circuit. If the IGBT is offered in a package with a co-pack diode, the co-pack diode is used as external diode. IGBTs and diode are at the same temperature (25°C and 125°C)

2. Turn-off losses include also the tail of the collector current.

Table 8.Collector-emitter diode

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
V _F	Forward on-voltage	I _F = 10 A I _F = 10 A, T _C = 125 °C		1.4	2.2	V V
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 7 \text{ A}, V_R = 40 \text{ V},$ di/dt = 100 A/µs (see Figure 21)		37 40 2.1		ns nC A
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 7 \text{ A}, V_R = 40 \text{ V},$ $T_j = 125 \text{ °C},$ $di/dt = 100 \text{ A/}\mu\text{s}$ <i>(see Figure 21)</i>		61 98 3.2		ns nC A

2.1 Electrical characteristics (curves)

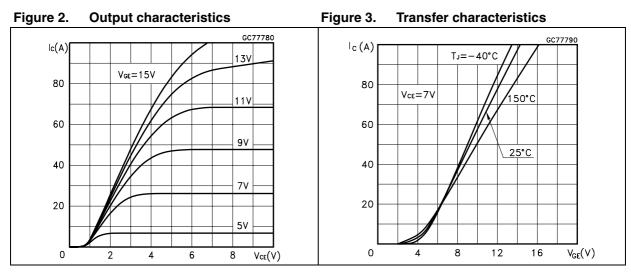


Figure 5.



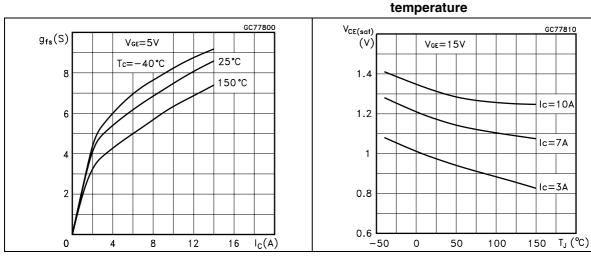
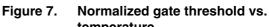
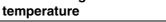
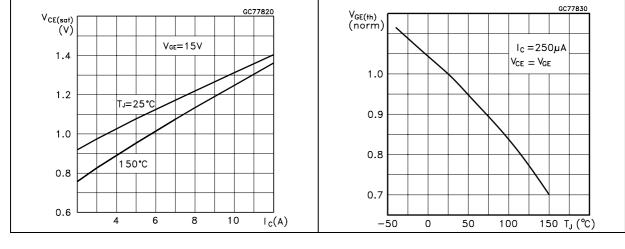


Figure 6. Collector-emitter on voltage vs. collector current





Collector-emitter on voltage vs.

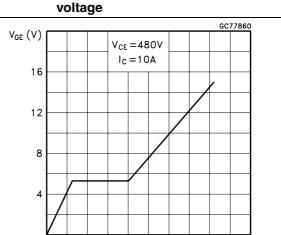


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 $Q_g(nC)$

GC77890

Figure 8. Normalized breakdown voltage vs. Figure 9. temperature



20

Switching losses vs. temperature

28

12

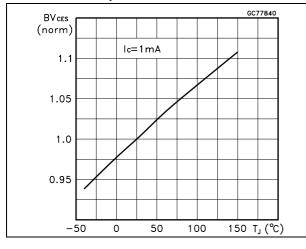
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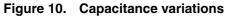
Figure 11.

E(mJ)

4

Gate charge vs. gate-emitter





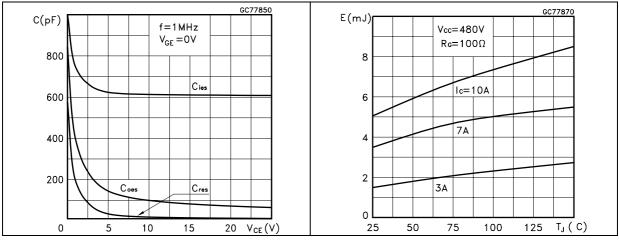
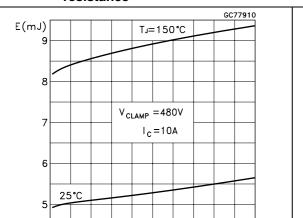


Figure 12. Switching losses vs. gate resistance



4

6

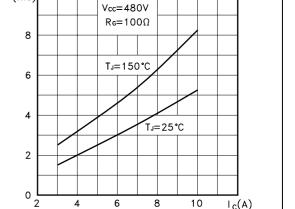


400

600

800

 $R_{G}(\Omega)$



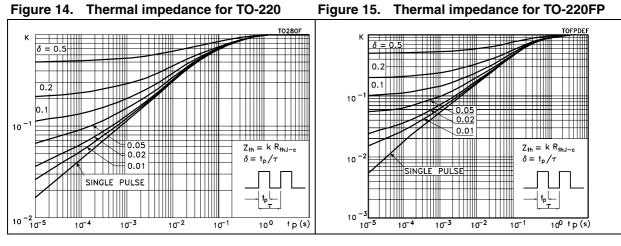
8

10

 $I_{c}(A)$

0

200



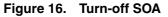
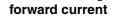
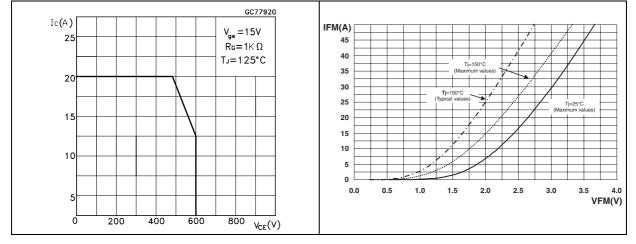


Figure 17. Forward voltage drop versus







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3 Test circuits

Figure 18. Test circuit for inductive load

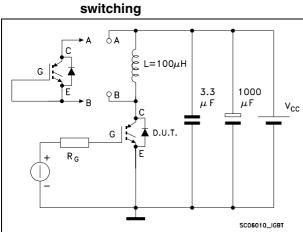
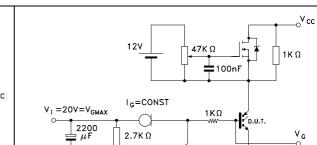


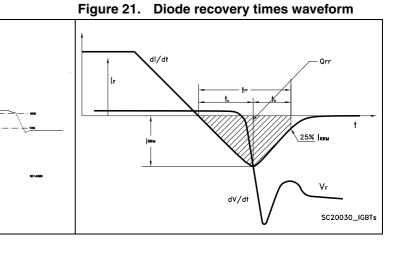
Figure 20. Switching waveforms



1K Ω

΄ Ρ_w

Figure 19. Gate charge test circuit





4 Package mechanical data

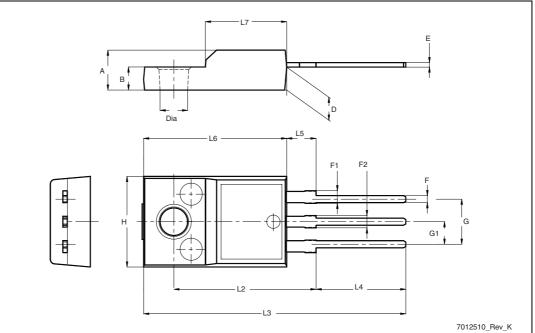
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.



Dim	mm.			
Dim.	Min.	Тур.	Max.	
A	4.4		4.6	
В	2.5		2.7	
D	2.5		2.75	
E	0.45		0.7	
F	0.75		1	
F1	1.15		1.70	
F2	1.15		1.70	
G	4.95		5.2	
G1	2.4		2.7	
н	10		10.4	
L2		16		
L3	28.6		30.6	
L4	9.8		10.6	
L5	2.9		3.6	
L6	15.9		16.4	
L7	9		9.3	
Dia	3		3.2	

Table 9.TO-220FP mechanical data

Figure 22. TO-220FP drawing



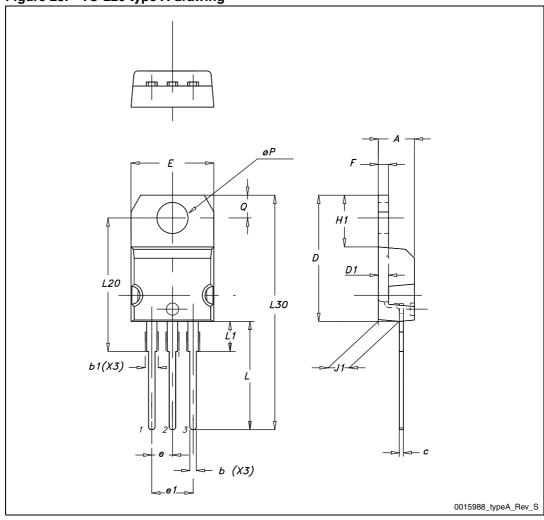


Dim	mm.			
Dim. —	Min.	Тур.	Max.	
А	4.40		4.60	
b	0.61		0.88	
b1	1.14		1.70	
С	0.48		0.70	
D	15.25		15.75	
D1		1.27		
E	10		10.40	
е	2.40		2.70	
e1	4.95		5.15	
F	1.23		1.32	
H1	6.20		6.60	
J1	2.40		2.72	
L	13		14	
L1	3.50		3.93	
L20		16.40		
L30		28.90		
ØР	3.75		3.85	
Q	2.65		2.95	

 Table 10.
 TO-220 type A mechanical data









5 Revision history

Table 11.	Document revision history
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Date	Revision	Changes
18-Nov-2005	1	New release.
16-Dec-2010	2	Inserted device in TO-220FP. Updated <i>Table 2: Absolute maximum ratings</i> , <i>Table 8: Collector-</i> <i>emitter diode</i> and packages mechanical data <i>Section 4:</i> <i>Package mechanical data</i> .
22-Sep-2011	3	Modified: unit value <i>Table 7 on page 5</i> , <i>Figure 2</i> and <i>Figure 3 on page 6</i> .



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